

Customer No.: 31561  
Application No.: 10/709,179  
Docket No.: 10544-US-PA

**AMENDMENTS**

**To the Claims:**

Claims 1-14. **Cancelled.**

Claim 15. (Currently amended) A method of fabricating bumps on a backside of a chip, comprising the steps of:

providing the chip with an active surface having at least a bonding pad thereon and the backside;

forming at least a bump pad on the backside of the chip; and

forming a bump directly on the bump pad.

Claim 16. (original) The method of claim 15, wherein the step of forming the bump pad on the backside of the chip further comprises:

forming a metallic layer on the backside of the chip; and

patterning the metallic layer to form the bump pad.

Claim 17. (original) The method of claim 15, wherein the step of forming the bump pad on the backside of the chip further comprises:

putting a mask on the backside of the chip, wherein the mask has at least an opening so that the backside of the chip is exposed;

forming a metallic layer over the mask and the exposed backside of the chip; and

removing the mask so that the remaining metallic layer on the backside of the

Customer No.: 31561  
Application No.: 10/709,179  
Docket No.: 10544-US-PA

chip becomes the bump pad.

Claim 18. (original) The method of claim 15, wherein before forming the bump pad on the backside of the chip, the method further comprises forming a protective film on the active surface of the chip.

Claim 19. (original) The method of claim 15, wherein the chip further comprises a passivation layer coated on the backside of the chip so that the passivation layer is removed before forming the bump pad on the backside of the chip.

Claim 20. (previously presented) The method of claim 15, wherein the step of forming the bump on the bump pad comprises performing one process selected from the group consisting of a patterning and electroplating process, a printing process, a bump-bonding process by a wire-bonding machine and a ball-implanting process.